

DATA SHEET

TDA6106Q Video output amplifier

Product specification
File under Integrated Circuits, IC02

1997 Mar 03

Video output amplifier

TDA6106Q

FEATURES

- No external heatsink required
- Black current measurement output for Automatic Black current Stabilization (ABS)
- Internal 2.5 V reference circuit
- Internal protection against positive appearing CRT flashover discharges
- Single supply voltage of 200 V
- Simple application with a variety of colour decoders
- Controlled switch-off behaviour.

GENERAL DESCRIPTION

The TDA6106Q is a monolithic video output amplifier with a 6 MHz bandwidth and is contained in a 9-lead plastic DIL-bent-SIL medium power package. The device uses high-voltage DMOS technology and is intended to drive the cathode of a CRT. To obtain maximum performance, the amplifier should be used with black current control.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TDA6106Q	DBS9MPF	plastic DIL-bent-SIL medium power package with fin; 9 leads	SOT111-1

BLOCK DIAGRAM

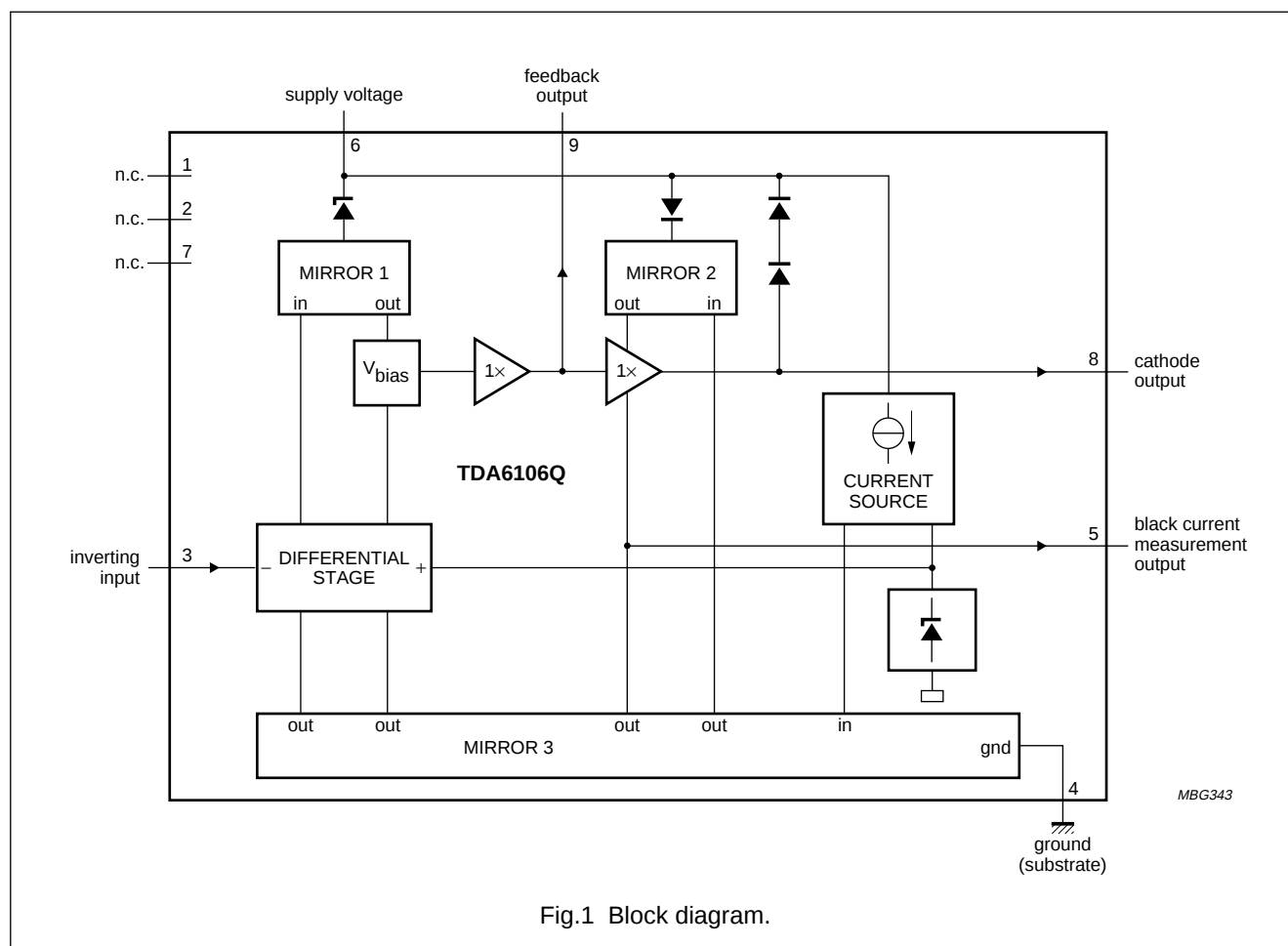


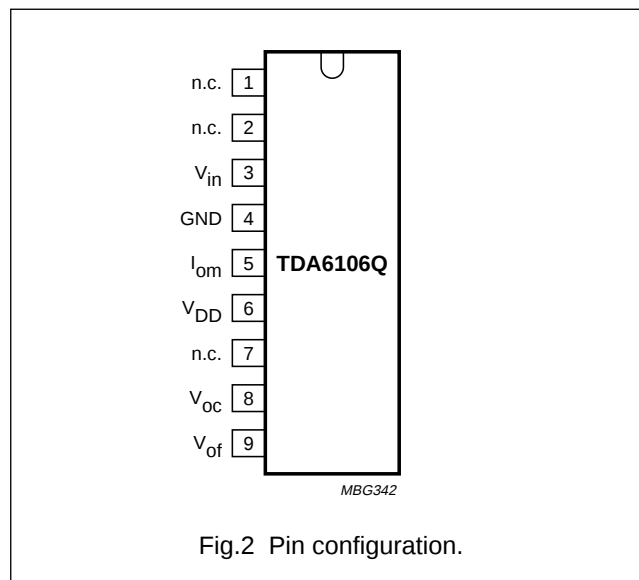
Fig.1 Block diagram.

Video output amplifier

TDA6106Q

PINNING

SYMBOL	PIN	DESCRIPTION
n.c.	1	not connected
n.c.	2	not connected
V_{in}	3	inverting input voltage
GND	4	ground, substrate
I_{om}	5	black current measurement output
V_{DD}	6	supply voltage
n.c.	7	not connected
V_{oc}	8	cathode output voltage
V_{of}	9	feedback output voltage



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134); voltages with respect to pin 4 (ground) unless otherwise specified; currents specified as in Fig.1.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DD}	supply voltage		0	250	V
V_{in}	inverting input voltage		0	8	V
V_{om}	black current measurement output voltage		0	6	V
V_{oc}	cathode DC output voltage		0	V_{DD}	V
V_{of}	feedback output voltage		0	V_{DD}	V
$I_{oc(l)}$	low non-repetitive peak cathode output current	flashover discharge = 100 μ C; note 1	0	5	A
$I_{oc(h)}$	high non-repetitive peak cathode output current	flashover discharge = 100 nC; note 2	0	10	A
P_{max}	maximum power dissipation		0	tbh	W
T_{stg}	storage temperature		-55	+150	$^{\circ}$ C
T_j	junction temperature		-20	+150	$^{\circ}$ C
V_{esd}	electrostatic discharge	note 3	-2000	+2000	V
		note 4	-300	+300	V

Notes

1. The cathode output is protected against peak currents (caused by positive voltage peaks during high-resistance flash) of 5 A maximum with a charge content of 100 μ C.
2. The cathode output is also protected against peak currents (caused by positive voltage peaks during low-resistance flash) of 10 A maximum with a charge content of 100 nC.
3. Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 k Ω resistor.
4. Machine model: equivalent to discharging a 200 pF capacitor through a 0 Ω resistor.

Video output amplifier

TDA6106Q

HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling MOS devices (see “*Handling MOS Devices*”).

QUALITY SPECIFICATION

Quality specification “*SNW-FQ-611 part E*” is applicable, except for ESD Human body model see Chapter “Limiting values”, and can be found in the “*Quality reference handbook*” (ordering number 9397 750 00192).

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER ⁽¹⁾	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient in free air	56	K/W
$R_{th\ j-c}$	thermal resistance from junction to case	12	K/W

Note

1. External heatsink not required.

CHARACTERISTICS

Operating range: $T_{amb} = -20$ to $+65$ °C; $V_{DD} = 180$ to 210 V (see note 1), $V_{om} = 1.4$ to 6 V.

Test conditions: $T_{amb} = 25$ °C; $V_{DD} = 200$ V; $V_{om} = 4$ V; $C_L = 10$ pF (C_L consists of parasitic and cathode capacitance); measured in test circuit of Fig.5; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{DD}	quiescent voltage supply current	$V_{ocDC} = 100$ V	2.8	3.0	3.3	mA
I_{bias}	input bias current (pin 3)	$V_{ocDC} = 100$ V	0	–	20	μA
V_{int}	internal reference voltage input stage	$V_{ocDC} = 100$ V	–	2.5	–	V
$I_{om(os)}$	offset current of black current measurement output	$I_{oc} = 0$ μA; $V_{in} = 1.5$ to $+3.5$ V; $V_{om} = 1.4$ to 6 V	–10	0	+10	μA
ΔV_{Tint}	temperature drift of internal reference voltage input stage	$V_{ocDC} = 100$ V	–	0.5	–	mV/K
$\frac{\Delta I_{om}}{\Delta I_{oc}}$	linearity of current transfer	$I_{oc} = -10$ μA to 3 mA; $V_{in} = 1.5$ to $+3.5$ V; $V_{om} = 1.4$ to 6 V	0.9	1.0	1.1	
$I_{of(max)}$	maximum peak output current (pin 9)	$V_{oc} = 20$ V to $V_{DD} - 30$ V	–	25	–	mA
$V_{oc(min)}$	minimum output voltage (pin 8)	$V_{in} = 3.5$ V	–	7	12	V
$V_{oc(max)}$	maximum output voltage (pin 8)	$V_{in} = 1.5$ V	$V_{DD} - 14$	$V_{DD} - 10$	–	V
GB	gain bandwidth product of open-loop gain $V_{os}/V_{i, dm}$	$f = 500$ kHz; $V_{ocDC} = 100$ V	–	0.52	–	GHz
BW_S	small signal bandwidth	$V_{ocAC} = 60$ V (p-p); $V_{ocDC} = 100$ V	5	6	–	MHz
BW_L	large signal bandwidth	$V_{ocAC} = 100$ V (p-p); $V_{ocDC} = 100$ V	4.7	5.7	–	MHz

Video output amplifier

TDA6106Q

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
t_{pd}	cathode output propagation delay time 50% input to 50% output	$V_{oc} = 50$ to 150 V square wave; $f < 1$ MHz; $t_{rin} = t_{fin} = 40$ ns; see Figs 3 and 4	38	49	60	ns
t_r	cathode output rise time 10% output to 90% output	$V_{oc} = 50$ to 150 V square wave; $f < 1$ MHz; $t_{fin} = 40$ ns; see Fig.4	62	74	87	ns
t_f	cathode output fall time 90% output to 10% output	$V_{oc} = 150$ to 50 V square wave; $f < 1$ MHz; $t_{rin} = 40$ ns; see Fig.4	62	74	87	ns
t_s	settling time 50% input to (99% < output < 101%)	$V_{oc} = 50$ to 150 V square wave; $f < 1$ MHz; $t_{rin} = t_{fin} = 40$ ns; see Figs 3 and 4	—	—	350	ns
SR	slew rate between 50 and 150 V	$V_{in} = 2$ V (p-p) square wave; $f < 1$ MHz; $t_{rin} = t_{fin} = 40$ ns	—	1200	—	V/ μ s
O_v	cathode output voltage overshoot	$V_{oc} = 50$ to 150 V square wave; $f < 1$ MHz; $t_{rin} = t_{fin} = 40$ ns; see Figs 3 and 4	—	1	—	%
PSRR	power supply rejection ratio	$f < 50$ kHz; note 2	—	60	—	dB

Notes

1. The rating of supply voltage is 250 V, but because of flash the maximum operating range for supply voltage is 210 V.
2. PSSR: The ratio of the change in supply voltage to the change in input voltage when there is no change in output voltage.

Video output amplifier

TDA6106Q

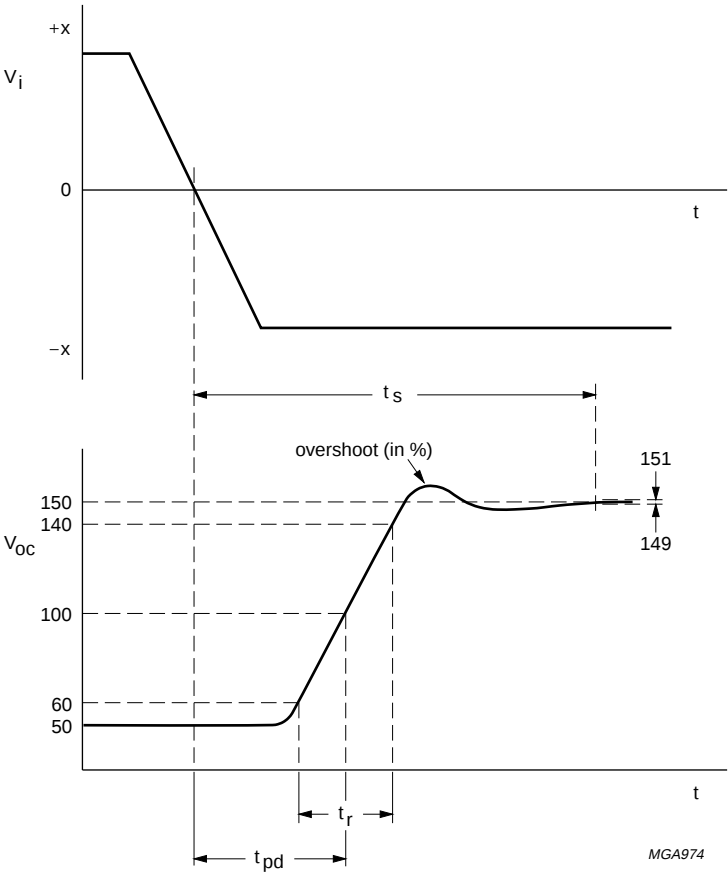


Fig.3 Output voltage (pin 8 rising edge) as a function of AC input signal.

Video output amplifier

TDA6106Q

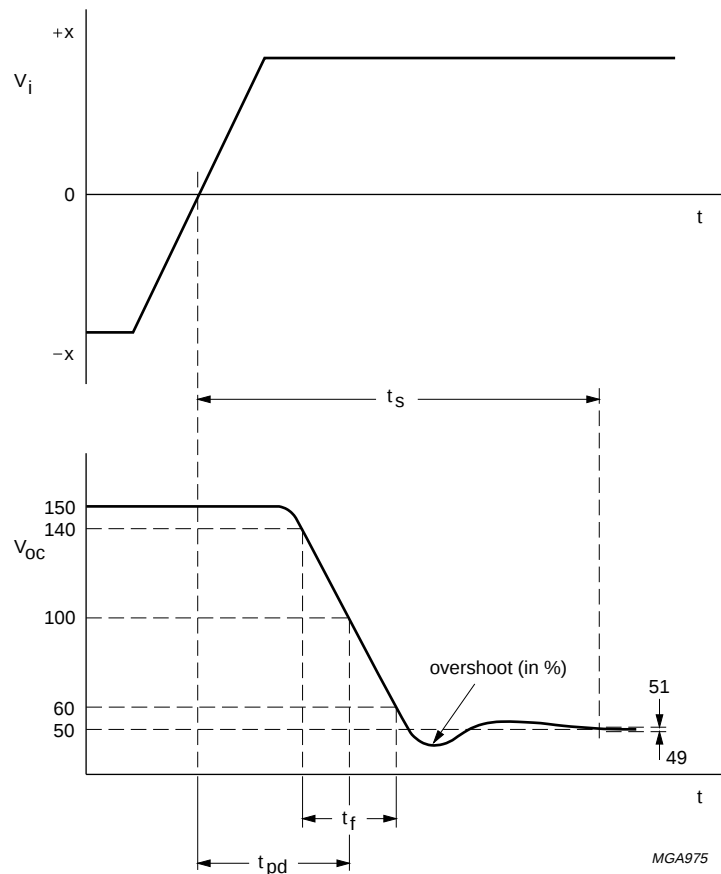


Fig.4 Output voltage (pin 8 falling edge) as a function of AC input signal.

Flashover protection

The TDA6106Q incorporates a protection diode against CRT flashover discharges that clamp the cathode output voltage to a maximum of $V_{DD} + V_{diode}$. To limit the diode current, an external 1.5 k Ω carbon high-voltage resistor in series with the cathode output and a 2 kV spark gap are needed (for this resistor-value, the CRT has to be connected to the main PCB). This addition produces an increase in the rise and fall times of approximately 7.5 ns and a decrease in the overshoot of approximately 1.3%.

V_{DD} to GND must be decoupled:

1. With a capacitor larger than 20 nF with good HF behaviour (e.g. foil). This capacitor must be placed as close as possible to pins 6 and 4, but definitely within 5 mm.
2. With a capacitor larger than 10 μ F on the picture tube base print (shared by three output stages).

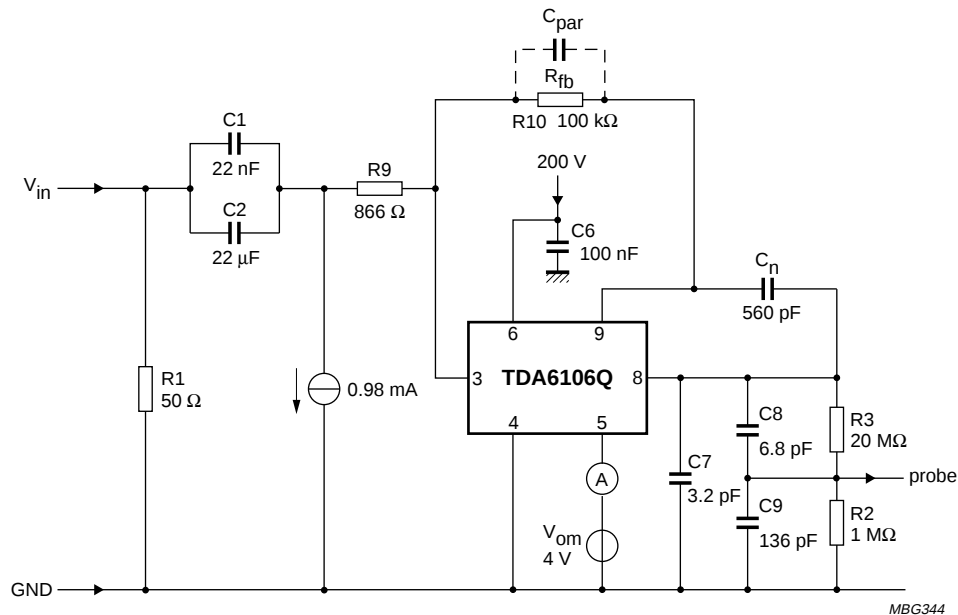
Switch-off behaviour

The output pins of the TDA6106Q are still under the control of the input pin for a supply voltage down to approximately 30 V.

Video output amplifier

TDA6106Q

TEST AND APPLICATION INFORMATION



$C_{par} = 150 \text{ fF}$.

Fig.5 Test circuit with feedback factor $\frac{1}{116}$.

Dissipation

With respect to dissipation, distinction must be made between static dissipation (independent of frequency) and dynamic dissipation (proportional to frequency).

The static dissipation of the TDA6106Q is due to supply currents and load currents in the feedback network and CRT.

$$P_{\text{stat}} = V_{\text{DD}} \times I_{\text{DD}} + V_{\text{oc}} \times I_{\text{oc}} - V_{\text{of}} \times \left(\frac{V_{\text{of}}}{R_{\text{fb}}} \right)$$

Where:

R_{fb} = value of feedback resistor.

I_{oc} = DC value of cathode current.

The dynamic dissipation equals:

$$P_{\text{dyn}} = V_{\text{DD}} \times (C_{\text{L}} + C_{\text{fb}} + C_{\text{int}}) \times f \times V_{\text{o(p-p)}} \times b$$

Where:

C_{L} = load capacitance.

C_{fb} = feedback capacitance.

C_{int} = internal load capacitance ($\approx 4 \text{ pF}$).

f = input frequency.

$V_{\text{o(p-p)}}$ = output voltage (peak-to-peak value).

b = non-blanking duty-cycle.

The IC must be mounted on the picture tube base print to minimize the load capacitance (C_{L}).

Video output amplifier

TDA6106Q

INTERNAL PIN CONFIGURATION

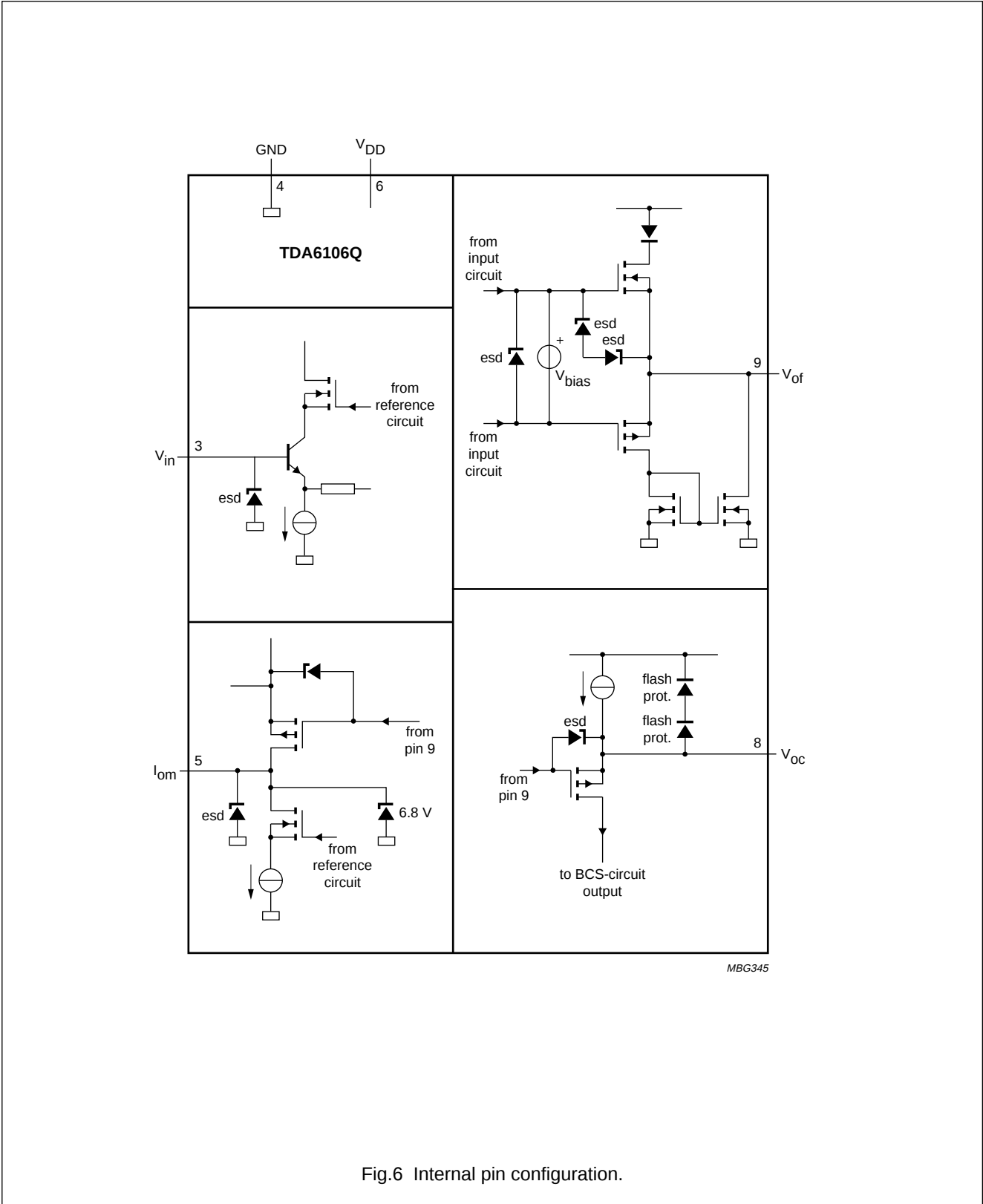


Fig.6 Internal pin configuration.

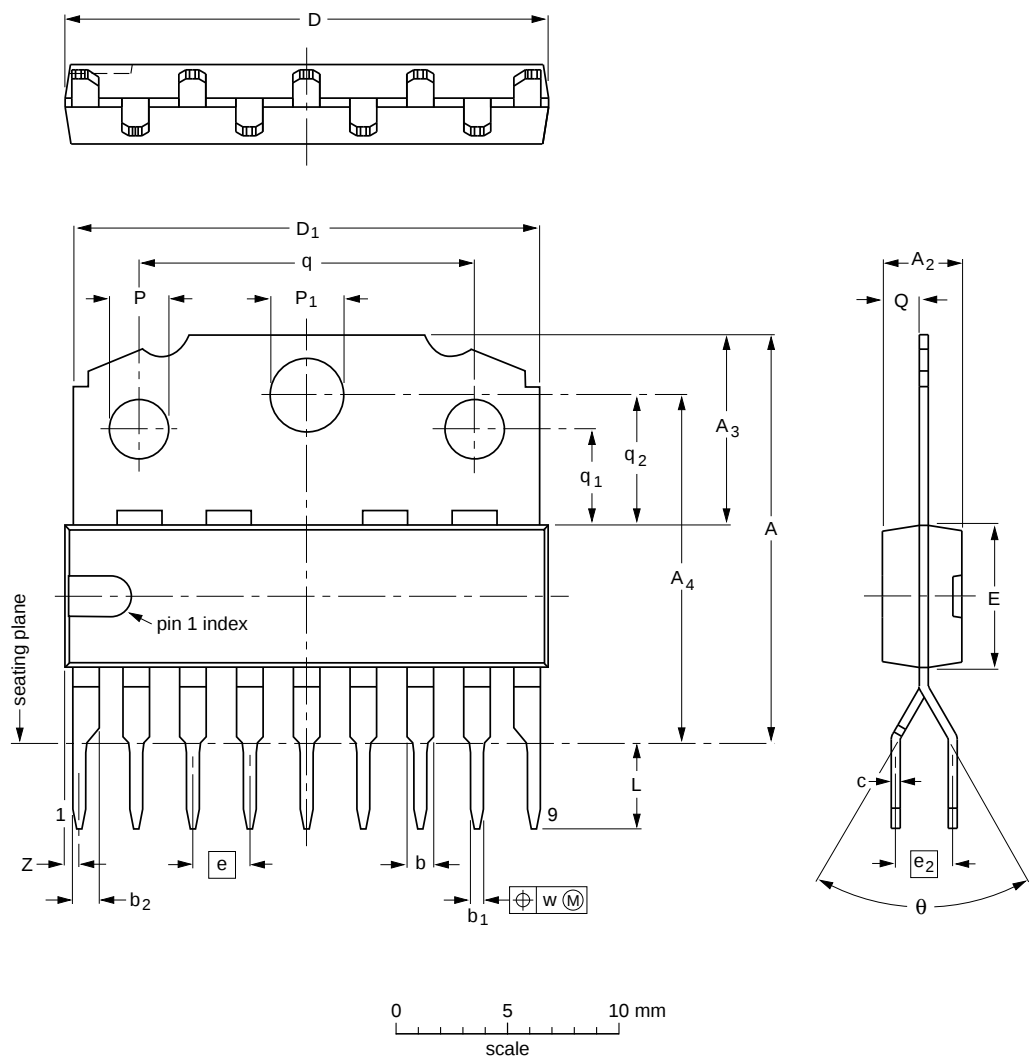
Video output amplifier

TDA6106Q

PACKAGE OUTLINE

DBS9MPF: plastic DIL-bent-SIL medium power package with fin; 9 leads

SOT111-1



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₂ max.	A ₃	A ₄	b	b ₁	b ₂	c	D ⁽¹⁾	D ₁	E ⁽¹⁾	e	e ₂	L	P	P ₁	Q	q	q ₁	q ₂	w	z ⁽¹⁾ max.	θ
mm	18.5 17.8	3.7	8.7 8.0	15.5 15.1	1.40 1.14	0.67 0.50	1.40 1.14	0.48 0.38	21.8 21.4	21.4 20.7	6.48 6.20	2.54	2.54	3.9 3.4	2.75 2.50	3.4 3.2	1.75 1.55	15.1 14.9	4.4 4.2	5.9 5.7	0.25	1.0	65° 55°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT111-1						92-11-17 95-03-11

Video output amplifier

TDA6106Q

SOLDERING**Introduction**

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113,
Tel. +61 2 9805 4455, Fax. +61 2 9805 4466

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213,
Tel. +43 1 60 101, Fax. +43 1 60 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,
220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773

Belgium: see The Netherlands

Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoprojekt, 15th floor,
51 James Bourchier Blvd., 1407 SOFIA,
Tel. +359 2 689 211, Fax. +359 2 689 102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS,
Tel. +1 800 234 7381

China/Hong Kong: 501 Hong Kong Industrial Technology Centre,
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,
Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S,
Tel. +45 32 88 2636, Fax. +45 31 57 1949

Finland: Sinikalliontie 3, FIN-02630 ESPOO,
Tel. +358 9 615800, Fax. +358 9 61580/xxx

France: 4 Rue du Port-aux-Vins, BP317, 92156 SURESNES Cedex,
Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427

Germany: Hammerbrookstraße 69, D-20097 HAMBURG,
Tel. +49 40 23 53 60, Fax. +49 40 23 536 300

Greece: No. 15, 25th March Street, GR 17778 TAVROS/ATHENS,
Tel. +30 1 4894 339/239, Fax. +30 1 4814 240

Hungary: see Austria

India: Philips INDIA Ltd, Shivsagar Estate, A Block, Dr. Annie Besant Rd.
Worli, MUMBAI 400 018, Tel. +91 22 4938 541, Fax. +91 22 4938 722

Indonesia: see Singapore

Ireland: Newstead, Clonskeagh, DUBLIN 14,
Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, TEL AVIV 61180,
Tel. +972 3 645 0444, Fax. +972 3 649 1007

Italy: PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3,
20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108,
Tel. +81 3 3740 5130, Fax. +81 3 3740 5077

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,
Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,
Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,
Tel. +9-5 800 234 7381

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,
Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,
Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO,
Tel. +47 22 74 8000, Fax. +47 22 74 8341

Philippines: Philips Semiconductors Philippines Inc.,
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Ul. Lukiska 10, PL 04-123 WARSZAWA,
Tel. +48 22 612 2831, Fax. +48 22 612 2327

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,
Tel. +7 095 755 6918, Fax. +7 095 755 6919

Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231,
Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,
2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000,
Tel. +27 11 470 5911, Fax. +27 11 470 5494

South America: Rua do Rocio 220, 5th floor, Suite 51,
04552-903 São Paulo, SÃO PAULO - SP, Brazil,
Tel. +55 11 821 2333, Fax. +55 11 829 1849

Spain: Balmes 22, 08007 BARCELONA,
Tel. +34 3 301 6312, Fax. +34 3 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM,
Tel. +46 8 632 2000, Fax. +46 8 632 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,
Tel. +41 1 488 2686, Fax. +41 1 481 7730

Taiwan: Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1,
TAIPEI, Taiwan Tel. +886 2 2134 2870, Fax. +886 2 2134 2874

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,
209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,
Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL,
Tel. +90 212 279 2770, Fax. +90 212 282 6707

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,
MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,
Tel. +1 800 234 7381

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,
Tel. +381 11 625 344, Fax. +381 11 635 777

For all other countries apply to: Philips Semiconductors, Marketing & Sales Communications,
Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

Internet: <http://www.semiconductors.philips.com>

© Philips Electronics N.V. 1997

SCA53

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

547047/1200/01/pp12

Date of release: 1997 Mar 03

Document order number: 9397 750 01869

Let's make things better.

**Philips
Semiconductors**



PHILIPS